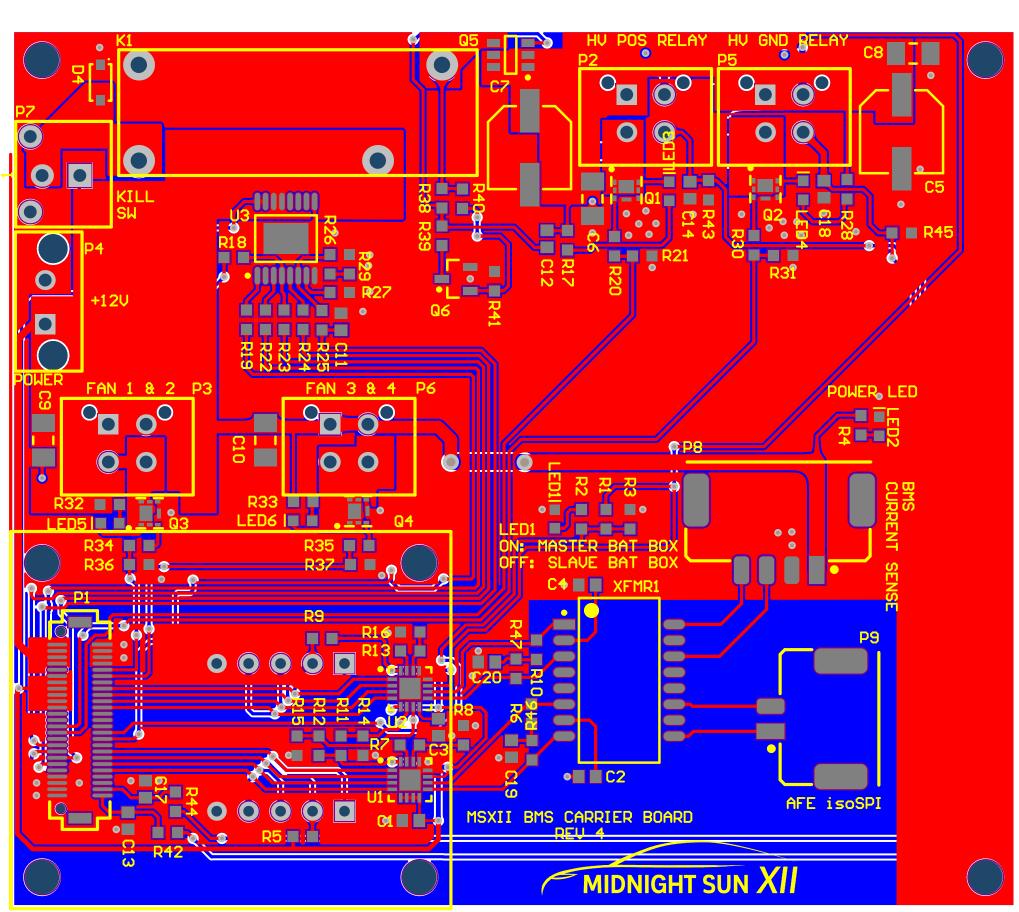
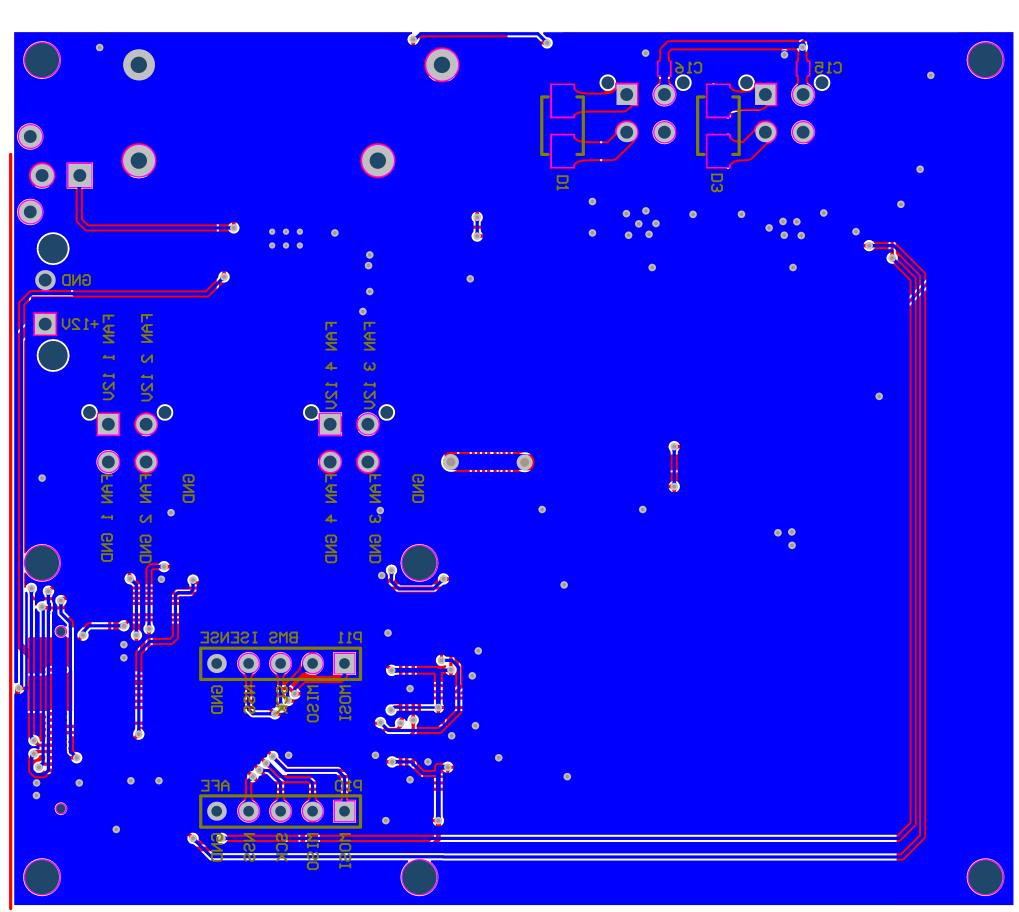


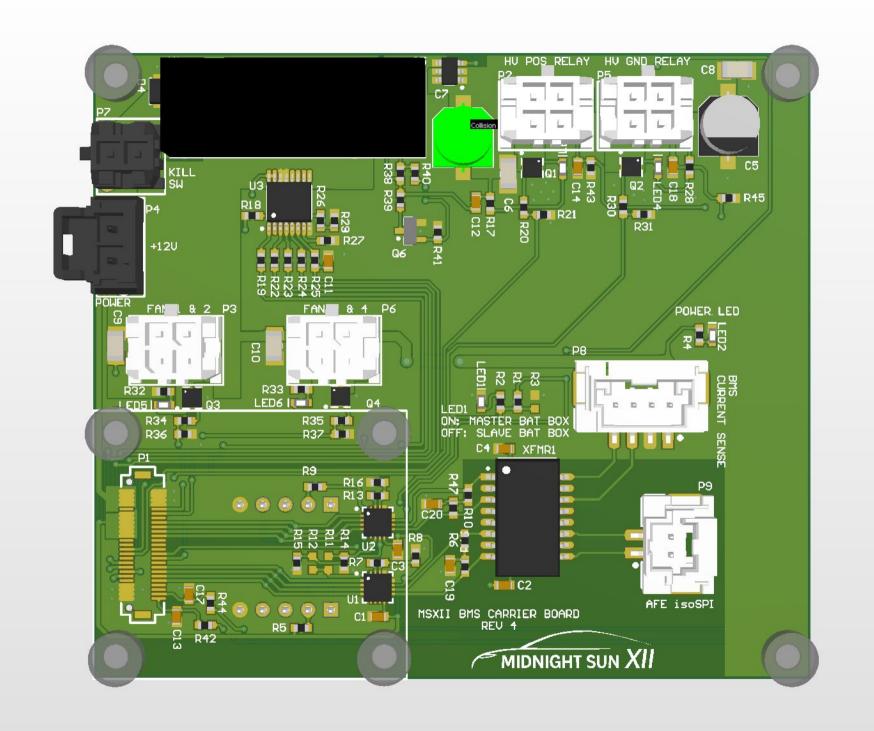
Bill of Materials		
Project:	BMS_Carrier_Board.PrjPcb	
Revision:	4.0	
Project Lead:	Aashmika Mali & Liam Hawkins	
Generated On:	2019-03-26 9:35:14 PM	
Production Quantity:	1	
Currency	CAD	
Total Parts Count:	95	



Company   Comp	,		1							
Control   Cont	LibRef	Designator	Manufacturer 1	Manufacturer Part Number 1	Supplier 1	Supplier Part Number 1	Supplier Unit Price 1	Supplier Order Qty	Supplier Subto	otal 1
Content   Cont	CAP CER 0.1UF 50V 10% X7R 0603		Kyocera AVX	06035C-104KAT2A			0.21	1	\$	0.21
Comparison of Comparison				GRM1885C1H200JA01D				1	\$	0.13
COP ALLINEST STATE AND COPY AN										0.21
Color   Colo			Panasonic	EEE1VA470WP		PCE3961CT-ND		i	s	0.55
Comparison   Com	CAP CER 2.2UF 100V ±20% X7R 1206				Digi-Key					
Open Company				CDM21CD72A226MA72I			0.55	1	\$	0.55
Control of the Cont				GRM31CR72A225MA73L				+		
Control   Cont		C10	<u>Murata</u>	GRM31CR72A225MA73L	Digi-Key					
Control of the first and the services   Column   Notice   Column								1	\$	0.21
Control of the Control of Contr	CAP CER 4.70F 25V 10% X5R 0603 CAP CER 0.11F 50V 10% X7R 0603									0.49
Control of the Part of the P								1	S	0.48
Color Color Del Color Del Color   Color Del					Digi-Key			· · · · · · · · · · · · · · · · · · ·	\$	0.48
Control of Control o									\$	0.48
Code State Por Vota Action									-	0.48
December 20   18 Max	CAP CER 10nF 50V 5% X7R 0603						0.48	1	\$	0.48
DODGE GENERATIVE GOVERNOR SECURITY OF THE SE									-	0.48
DODGE CHAPP FOOT NAME (DODGE)   DO   DODGE DEED   DO   DOGGE   DOGGE DEED   DOGGE										0.55
REAL PROPERTY OF A CAMERY   C.   C.   C.   C.   C.   C.   C.   C										0.29
LEPTICAL PLANT   1.00								-	3	
LEG OPERITATION OF THE PROPERTY   LEG								1	\$	5.44 0.19
LES PELLON CERES 1 1998   1690   1   3   0   0   1   3   0   0   1   3   0   0   1   3   0   0   1   3   0   0   1   3   0   0   1   3   0   0   1   3   0   0   0   1   3   0   0   0   0   0   0   0   0   0									s	0.19
EDITION CLARK PLANSON   EST	LED YELLOW CLEAR 2.1V 0603	LED3	Wurth Electronics	150060YS75000	Digi-Key	732-4981-1-ND	0.19		\$	0.19
LO   PULLOY CLAR 2 1 19000   LEFO   Wind Exercises   10000077000   Pulses   Left   L									\$	0.19
CORPORT DESIGNATION   PT					Digi-Key Digi-Kev			1	S	0.19
CORNING MAGNETT COD   P2   1566   0.00000077   0.00460   1.70   1   3   1   1   1   1   1   1   1   1								111	\$	1.87
CONNYSCIALINENTICSUST   PA	CONN 4POS MICROFIT (2x2)				Digi-Key		1.79	· · · · · · · · · · · · · · · · · · ·		1.79
CONN-PICE MERCHT FOOD									-	1.79
CON-PICE MERCHET DOT				0430450427		WM10667-ND				1.79
CONNECTED PROPERTY   PS	CONN 4POS MICROFIT (2x2)	P6	Molex		Digi-Key	WM10667-ND	1.79	1	\$	1.79
CONTROL   CONT					Digi-Key					1.12
CORNINGS (EACH MALE CIT   P10   Make										1.04
CONTINUES FEAD MALE 01										0.32
MOSPET HOUSE DE ALT UN PAPON LOSS   1   3   0   0   1   3   0   0   0   0   0   0   0   0   0	CONN 5POS HEADR MALE 0.1"	P11	Molex	0022284050				1	\$	0.32
MODERT NOT 12 A 2 NO 6-POPN (200)   1   5   0   0   1   5   0   0   1   5   0   0   0   1   5   0   0   0   0   0   0   0   1   5   0   0   0   0   0   0   0   0   0	MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q1	Infineon	IRLHS6342TRPBF	Digi-Key		0.9	1	\$	0.90
MOSFET HOLD NO. A. 104 FORM 1200   0.00   1   3   0.00   1   3   0.00   1   3   0.00   1   3   0.00   0.0										
Interest   Content   Con	MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q2	Infineon	IRLHS6342TRPBF	Digi-Key		0.9	1	\$	0.90
MOSET FI CHINA 17, 2 UN POPULOD	MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q3	Infineon	IRLHS6342TRPBF	Digi-Key		0.9	1	s	0.90
MOSETT-CHU 2012-1252-16	, ,							-	<u> </u>	
MORPET NOT 1000 3100	MOSFET N-CH 30V 8.7A 2.1W 6-PQFN (2x2)	Q4	Infineon	IRLHS6342TRPBF	Digi-Key		0.9	1	\$	0.90
RES 0.0 CMM LAW (903)			STMicroelectronics					1	\$	0.87
RES DICTOR 11 1 1 1										0.25
RES ATRO-MIN 15/109/0803   RES   Yassee   RECOMPRESSION   Dig May   3114_0706/RECTAL   0.013   1   \$   0.0								1	\$	0.13
RES 40 CMM 1% 1/10W 0003 R7 Yango R5 14 CMM 1% 1/10W 0003 R7 Yango R5 14 CMM 1% 1/10W 0003 R7 Yango R5 14 CMM 1% 1/10W 0003 R7 R5 16 CMM 1% 1/10W 0003 R7 R5 17 CMM 1% 1/10W 0003 R7 R5 18 CMM 1% 1/10W 0003 R7 R5 17 CMM 1% 1/10W 0003 R7 R5 18 CMM 1% 1/10W 0003 R7 R5	RES 4.7K OHM 1% 1/10W 0603	R4	Yageo Phycomp	RC0603FR-074K7L				1	\$	0.13
RES 1.40 CMM 1% 1/10W 0603 RB Yappo RES 04 CMM 1% 1/10W 0603 RB Yappo RB Yappo RES 04 CMM 1% 1/10W 0603 RB Yappo RB Y			Yageo	RC0603FR-072KL		311-2.00KHRCT-ND		1	\$	0.13
RES 04.0 FM 15 1170W 0603			Yaneo Vaneo	RC0603FR-071K4I		311-1 40KHRCT-ND		1	\$	0.47
RES 2K CMM 1% 1/10W 0003 RES 14 CMM 1% 1/10W 0003 RES 15 CMM 1% 1/10W 0003 RES 15 CMM 1% 1/10W 0003 RES 16 CMM 1% 1/10W 0003 RES 17 CMM 1% 1/10W 0003 RES 17 CMM 1% 1/10W 0003 RES 17 CMM 1% 1/10W 0003 RES 18 CMM 1% 1/10W 0003 RES 18 CMM 1% 1/10W 0003 RES 17 CMM 1% 1/10W 0003 RES 18 CMM 1% 1/10W 0003 RES 17 CMM 1% 1/10W 0003 RES 18 CMM 1% 1/10W 0003 RES 17 CMM 1% 1/10W 0								1		0.13
RES 1-00 CMM 15th 1700V 0003 R13 Yasso RC000FR-07105L Dig-New 3311-1400R6CT-ND 0.22 1 \$ 0.0 RES 0.0 CMM 140V 0003 R15 Value Dig-New 3411-050RCT-ND 0.22 1 \$ 0.0 RES 0.0 CMM 15th 1700V 0003 R15 Yasso R15 Yass			<u>Yageo</u>		Digi-Key			1	\$	0.13
RES 0.0 CMM 14W 09030 R15 Vishay Dale CREV/09050000000APP Disk-Key 61-0.05867-ND 0.23 1 \$ 0.0 R15 00 CMM 14W 09030 R15 Vishay Dale CREV/0905000000APP Disk-Key 61-0.05867-ND 0.23 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R16 Vishay Dale CREV/0905000APP Disk-Key 61-0.05867-ND 0.23 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R17 Vishay Dale CREV/090500APP Disk-Key 61-0.05867-ND 0.23 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R17 Vishay Dale CREV/09050APP Disk-Key 61-0.05867-ND 0.23 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R19 Vishay Dale CREV/09050APP DISK-Key 61-0.05867-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R19 Vishay Dale CREV/09050APP DISK-Key 61-0.05867-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R21 Vishay Dale CREV/09050APP R19967, Disk-Key 311-2.100660C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R21 Vishay Dale CREV/09050APP R19967, Disk-Key 311-2.100660C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R22 Vishay Dale CREV/09050APP R19967, Disk-Key 311-2.100660C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R23 Vishay Dale CREV/09050APP R19967, Disk-Key 311-2.100660C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R23 Vishay Dale CREV/09050APP R19967, Disk-Key 311-2.100660C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R23 Vishay Dale CREV/09050APP R19967, Disk-Key 311-2.100660C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R23 Vishay Dale CREV/09050APP R19967, Disk-Key 311-2.100660C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R23 Vishay Dale CREV/09050APP R19967, Disk-Key 311-2.100660C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R23 Vishay Dale CREW/09050APP R19967, Disk-Key 311-2.00060C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R23 Vishay Dale CREW/09050APP R19967, Disk-Key 311-2.00060C1-ND 0.13 1 \$ 0.0 R15 00 CMM 15W 17W 09030 R28 Vishay Dale CREW/09050APP R199670APP									\$	0.47
RES 604 CMM 1% 11/00/ 0603								1	S	0.13
RES 4.7K CPM 1% L/10W 0603   R17			Vishay Dale						\$	0.23
RES 4.7K OFM 1% 1/10W 0603									\$	0.13
RES 4.7K CHM 1% 1/00W 0903								_	-	0.13
RES 100 M 1% 1/10W 0603 R21 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-22 HRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R22 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R23 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R23 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R24 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R24 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R25 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R26 Physorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R27 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R27 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R27 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R27 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R20 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R20 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R20 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R20 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R20 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R23 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 4.7K OFM 1% 1/10W 0603 R23 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17/014PRCT-ND 0.13 1 \$ 0.0 RES 10K OFM 1% 1/10W 0603 R23 R23 Yasso Phycorp RC0603FR 07/10K1, Digit-Rey 311-17								1	s	0.13
RES 4.7K CHM 1% 1/10W 0903   R22   Yasse Phycomp   R00803R 074KTL   Dig-Key   3114.7U04RCT-ND   0.13   1   \$ 0.0	RES 22.1 OHM 1% 1/10W 0603				Digi-Key				-	0.13
RES 4.7K OHM 1% 1/10W 0603   R24   Yagoo Phroomp   RC0003FR.074KT, Digh-Rey   3114-70KHRC1-ND   0.13   1   \$   0. \$									5	0.13
RES 4.7K CMM 19k 1/10W 0603									S	0.13
RES 4.7K OFM 1% 1/10W 0603	RES 4.7K OHM 1% 1/10W 0603	R24	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13		\$	0.13
RES 47K CMM 19 1/10W 0603	RES 4.7K OHM 1% 1/10W 0603		100,000 111,00010					1	\$	0.13
RES 4.7K OHM 1% 1/10W 0803   R28										0.21
RES 24. OHM 1% 1/10W 0603   R29								11	\$	0.13
RES 10K OHM 1% 1/10W 0603   R31		R29	Yageo		Digi-Key		0.13			0.13
RES 4.7K CMM 19 1/10W 0603			Yageo Yageo Physones						1:	0.13
RES 4.7K CHM 19: 1/10W 0603   R33									s	0.13
RES 22.1 CMM 1% 1/10W 0803	RES 4.7K OHM 1% 1/10W 0603	R33	Yageo Phycomp	RC0603FR-074K7L	Digi-Key	311-4.70KHRCT-ND	0.13		\$	0.13
RES 10K OHM 1% 1/10W 0603   R36	RES 22.1 OHM 1% 1/10W 0603				Digi-Key			1	\$	0.13
RES 10K OHM 1% 1/10W 0603   R37					Digi-Key Digi-Key			1 1		0.13
RES 330 OHM 1% 1/10W 0603   R38   TE Connectify   CRSCQ060967330R   Digi-Key   A129667TE-ND   RES 16W M5% 1/10W 0603   R39   Yagoo   RC060318-071EL   Digi-Key   311-10KGRCT-ND   0.13   1   5   0.			Yageo Phycomp					<u> </u>	š	0.13
RES 0.0 O-MM 1/4W 0603   R40   Vishay Date   CRCW06030000000000000000000000000000000000	RES 330 OHM 1% 1/10W 0603	R38	TE Connectivity		Digi-Key					
RES 10K OHM 1% 1/10W 0603   R41   Yasee Phycomp   R00603FR-0710KL   Dig-Key   311-10.004RGT-ND   0.13   1   \$ 0.0										0.13
RES 1K OHM 5k 1/10W 0603   R42   Yappe   RC0603R-R071KL   Digi-Key   311-1,0KGRCT-ND   0.13   1   \$ 0.0										0.23
RES 10K OHM 1% 1/10W 0603   R43   Yagoo Phycorp   R00003FR-0710KL   Digi-Key   311-10,00K-RCT-ND   0.13   1   \$ 0.0			Yageo Yageo	RC0603JR-071KL		311-1.0KGRCT-ND			s	0.13
RES 10K OPM 1% 1/10W 0803	RES 10K OHM 1% 1/10W 0603				Digi-Key	311-10.0KHRCT-ND	0.13			0.13
RES 82 OHM 0.1% 1/10W 0603   R46   Panasonic   ERAJAERSCOV   Digi-Key   PSCDBCT-ND   0.47   1   \$ 0.0								+ 1		0.13
RES 62 OHM 0.1% 1/10W 0603   R47   Panesonic   ER3AEB620V   Dig-Key   P620BCT-ND   0.47   1   \$ 0.0				ERA3AEB620V		P62DBCT-ND		1		0.13
C   IC   IC   IC   IC   IC   IC   IC			Panasonic							0.47
IC ISOSPI COMM INTERFACE LTG820IUD   U2   Analog Defices / Linear   LTG820IUD#PBF   Digi-Key   LTG820IUD#PBF-ND   7.44   1   \$ 7.	IC ISOSPI COMM INTERFACE LTC6820IUD	U1		LTC6820IUD#PBF	Digi-Key	LTC6820IUD#PBF-ND	7.44	1	\$	7.44
IC PULSE XFMR 1CT:1CT350UH SNID   XFMR1   Bourns   PT61018AAPELS   Digi-Key   Telegraph   THe   T. S.										
IC PULSE XFMR 1CT:1CT 350 UH SMD   XFMR1   Bourns   PT61018APELS   Digi-Key   ND   ND   S 5.12   1   \$ 5.	IC ISOSPI COMM INTERFACE LTC6820IUD	U2		LTC6820IUD#PBF	Digi-Key		7.44	1	\$	7.44
IC PULSE XFMR 1CT:1CT 350UH SMD         XFMR1         Bourns         PT61018AAPELS         Digi-Key         PT61018AAPELSCT- ND         5.12         1         \$         5.	IC HSD Dual-Channel 40V 1KOhm	LI3	Texas Instruments	TPS2H000BOPWPRO1	Digi-Kev					
TO POLSE AFMIR TO THE SOUTH SMU AFMIRT BOUTTS PTG TO BARAFELS DIG NEW ND 5.12 1 \$ 5.								<del> </del>	<del>                                     </del>	
	IC PULSE XFMR 1CT:1CT 350UH SMD	XFMR1	Bourns	PT61018AAPEL-S	Digi-Key		5.12	1	\$	5.12
								Total:	\$	61.90







## **Electrical Rules Check Report**

Class	Document	Message
Warning	BMS Carrier - Firmware Contactor	Global Power-Object 3V3 at 2600mil,5100milhas been reduced to local level by presence of
	Control.SchDoc	port at 2800mil,4500mil
Warning	BMS Carrier - AFE Interface.SchDoc	incorrect link between project variant "BMS Carrier - Slave Battery Box" and schematic
		component Component R6 62R
Warning	Controller_Board_Interface.SchDoc	Net 3V3 has no driving source (Pin C1-1,Pin C3-1,Pin C15-1,Pin C16-1,Pin P1-40,Pin
		P1-41,Pin P1-42,Pin P1-43,Pin P1-44,Pin P1-45,Pin P2-3,Pin P5-3,Pin R1-1,Pin R5-1,Pin
		R9-1,Pin R11-1,Pin R12-1,Pin R18-2,Pin U1-5,Pin U1-6,Pin U1-7,Pin U1-8,Pin U1-11,Pin
Error	BMS Carrier - Connectors.SchDoc	U1-16 Pin U2-5 Pin U2-8 Pin U2-11 Pin U2-16) Net 12V_CONTACTOR_COIL_SW contains multiple Input Ports (Porl
		12V CONTACTOR COIL SW,Port 12V CONTACTOR COIL SW)
Error	BMS Carrier - Battery Relay	Net 12V_CONTACTOR_COIL_SW contains multiple Input Ports (Port
	Controls.SchDoc	12V_CONTACTOR_COIL_SW,Port 12V_CONTACTOR_COIL_SW,Port
		HV GND RELAY 12V SW.Port HV PWR RELAY 12V SW)
Error	BMS Carrier - Battery Relay	Net 12V_CONTACTOR_COIL_SW contains multiple Input Ports (Port
	Controls.SchDoc	HV GND RELAY 12V SW,Port HV PWR RELAY 12V SW)
Error	BMS Carrier - Battery Relay	Net NetD1_1 contains multiple Input Ports (Port HV_PWR_RELAY_GND,Port
	Controls.SchDoc	HV_PWR_RELAY_GND)
Error	BMS Carrier - Battery Relay	Net NetD3_1 contains multiple Input Ports (Port HV_GND_RELAY_GND,Porl
	Controls.SchDoc	HV_GND_RELAY_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net NetLED5_2 contains multiple Input Ports (Port FAN_1_GND,Port FAN_1_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net NetLED6_2 contains multiple Input Ports (Port FAN_2_GND,Port FAN_2_GND)
Error	BMS Carrier - Fan Controls.SchDoc	Net PA9_FAN_2_PWM contains multiple Input Ports (Port PA9_FAN_2_PWM,Port
		PA9_FAN_2_PWM)
Error	BMS Carrier - Fan Controls.SchDoc	Net PA10_FAN_1_PWM contains multiple Input Ports (Port PA10_FAN_1_PWM,Port
		PA10_FAN_1_PWM)
Warning	Controller_Board_Interface.SchDoc	Net PB0_MOSFET_SOFT_START_INPUT has no driving source (Pin P1-17)
Error	BMS Carrier - AFE Interface.SchDoc	Net PB0_MOSFET_SOFT_START_INPUT has only one pin (Pin P1-17)
Warning	BMS Carrier - Battery Relay	Unconnected line (4850mil,2100mil) To (4950mil,2100mil)
	Controls.SchDoc	

Tuesday 26 Mar 2019 9:36:55 PN. Page 1 of 1

**Design Rules Verification Report**Filename : C:\Users\Aashmika Mali\Documents\First Year\Midnight Sun\hardware\MSXII\_BN

Warnings 0 Rule Violations 99

## Warnings Total 0

Rule Violations	
Clearance Constraint (Gap=0.152mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ( (All) )	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.203mm) (Max=2.54mm) (Preferred=0.203mm) (All)	0
Power Plane Connect Rule(Direct Connect)(Expansion=0.508mm) (Conductor Width=0.254mm) (Air Gap=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=5.08mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)	99
Silk To Solder Mask (Clearance=0.254mm) (Disabled)(IsPad),(All)	0
Silk to Silk (Clearance=0.254mm) (Disabled)(All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	99

Minimum Solder Mack Sliver (Can. 0.2E4mm) (All) (All)
Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All) Minimum Solder Mask Sliver Constraint: (0.244mm < 0.254mm) Between Pad C13-1(9.324mm,7.675mm) on Top Layer And Pad
Miliminal Solder Mask Silver Constraint: (0.244mm < 0.254mm) between Pad P1-(4mm,22.05mm) on Multi-Layer And Pad P1-(5.5mm,22.8mm) on To
Minimum Solder Mask Sliver Constraint: (0.105mm < 0.254mm) Between Pad P1-(4mm,7.95mm) on Multi-Layer And Pad P1-(5.5mm,7.2mm) on Top
Millimum Solder Mask Sliver Constraint: (0.1051mm < 0.254mm) Between Pad Q1-1(48.025mm,57.8mm) on Top Layer And Pad
Minitidan 25mm Mask mover Constraint: (0.047mm < 0.254mm) Between Pad Q1-2(48.025mm,57.15mm) on Top Layer And Pad
Minis (48:025mm, Maskmoni) ver Constraint: (0.047mm < 0.254mm) Between Pad Q1-3(48.025mm, 56.5mm) on Top Layer And Pad
Mini/(48/95olde 5 Mini/(48/95o
MinBr(4.8h9Soride; 5M4\$km8hi)ver Constraint: (0.047mm < 0.254mm) Between Pad Q1-4(49.875mm, 56.5mm) on Top Layer And Pad
Minb(42n835mm, 5/435mm) on Top Layer And Pad
Minif(46/95olde FM45kn95ii)er Constraint: (0.202mm < 0.254mm) Between Pad Q1-4(49.875mm,56.5mm) on Top Layer And Pad
Minb(4bh9Solde,5Máskn8hi)ver Constraint: (0.047mm < 0.254mm) Between Pad Q1-5(49.875mm,57.15mm) on Top Layer And Pad
Q1n/b/(42/0855tder, M/a8kn9ti).er Constraint: (0.187mm < 0.254mm) Between Pad Q1-7(48.95mm, 57.45mm) on Top Layer And Pad
Mini Ath P Solde F M 43 kn Shilver Constraint: (0.047mm < 0.254mm) Between Pad Q2-1(59.075mm, 57.884mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q2-2(59.075mm,57.234mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q2-3(59.075mm,56.584mm) on Top Layer And Pad
Mahi/(ճարթեներ Maskr Stiver Constraint: (0.202mm < 0.254mm) Between Pad Q2-3(59.075mm,56.584mm) on Top Layer And Pad
Manacom Bolifeet Manacom Silver Constraint: (0.047mm < 0.254mm) Between Pad Q2-4(60.925mm,56.584mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q2-4(60.925mm,56.584mm) on Top Layer And Pad
աներին արդաներ արդան ա
Man Brown Straint: (0.047mm < 0.254mm) Between Pad Q2-5(60.925mm,57.234mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad Q2-7(60mm,57.534mm) on Top Layer And Pad Q2-8(60mm,56.494mm
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q3-1(10.4mm,30.525mm) on Top Layer And Pad
Qֈֈֈութանագրան (0.047mm < 0.254mm) Between Pad Q3-2(11.05mm,30.525mm) on Top Layer And Pad
Quanta (11.7mm,30.525mm) on Top Layer And Pad
Qֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈֈ
Mana (11.7mm,32.375mm) on Top Layer And Pad
Man եր (Lin D Solde B Mass Sol
Manikitun7 Spotde AM 45 km Sniver Constraint: (0.202mm < 0.254mm) Between Pad Q3-4(11.7mm,32.375mm) on Top Layer And Pad
Mana (11.05mm, 32.375mm) on Top Layer And Pad
่ Mahir (ในท4 Bortu อิวเทรียทรง) ver Constraint: (0.187mm < 0.254mm) Between Pad Q3-7(10.75mm,31.45mm) on Top Layer And Pad
Mana (14-1(26.975mm, 30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-2(27.625mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-3(28.275mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.202mm < 0.254mm) Between Pad Q4-3(28.275mm,30.695mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-4(28.275mm, 32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-4(28.275mm,32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.202mm < 0.254mm) Between Pad Q4-4(28.275mm,32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad Q4-5(27.625mm, 32.545mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.187mm < 0.254mm) Between Pad Q4-7(27.325mm,31.62mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-1(41.115mm,66.966mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-2(41.115mm,67.916mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.198mm < 0.254mm) Between Pad Q5-4(38.385mm,68.866mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.176mm < 0.254mm) Between Pad Q5-5(38.385mm,67.916mm) on Top Layer And Pac
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-1(30.325mm,11mm) on Top Layer And Pad U1-17(31.75mm,10.25r Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-1(30.325mm,11mm) on Top Layer And Pad U1-2(30.325mm,10.5m
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-10(33.175mm,10mm) on Top Layer And Pad
Minini (23. 575 der Mask 18 liver Constraint: (0.022 mm < 0.254 mm) Between Pad U1-10(33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm) on Top Layer And Pad U1 0/33.175 mm, 10 mm on Top Layer And Pad U1 0/33.175
Minim (2ni. 35) one Top Layer And Pad U1-9(33.175mm,9.5m
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-11(33.175mm,10.5mm) on Top Layer And Pad
Minita(BB: StödenMaskrish)ver Constraint: (0.022mm < 0.254mm) Between Pad U1-11(33.175mm,10.5mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-12(33.175mm,11mm) on Top Layer And Pad
Minin/(ini. 55inder, Ma35r5inver Constraint: (0.047mm < 0.254mm) Between Pad U1-13(32.5mm,11.675mm) on Top Layer And Pad
- U1-14(32mm,11.675mm)

Minimum Solder Mask Sliver (Gap=0.254mm) (All),(All)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-13(32.5mm,11.675mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-14(32mm,11.675mm) on Top Layer And Pad
Minifo(ini. Soute) Maskinshoer Constraint: (0.022mm < 0.254mm) Between Pad U1-14(32mm,11.675mm) on Top Layer And Pad
Minin/(iii). Solder, Maskirshiver Constraint: (0.047mm < 0.254mm) Between Pad U1-15(31.5mm,11.675mm) on Top Layer And Pad
Minin (Ani resolute) with several transfer of the seve
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-16(31mm,11.675mm) on Top Layer And Pad
Minin/(ini. Soituer, Massinstryler Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm, 10.25mm) on Top Layer And Pad
M1n2(30n3 25otder, Massinsi)ver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm, 10.25mm) on Top Layer And Pad U1-3(30.325mm, 10mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-4(30.325mm,9.5mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-5(31mm,8.825mm)
byfinimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-6(31.5mm,8.825mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-7(32mm,8.825mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-8(32.5mm,8.825mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U1-17(31.75mm,10.25mm) on Top Layer And Pad U1-9(33.175mm,9.5mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-2(30.325mm,10.5mm) on Top Layer And Pad U1-3(30.325mm,10mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-3(30.325mm,10mm) on Top Layer And Pad U1-4(30.325mm,9.5mm) d
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-5(31mm,8.825mm) on Top Layer And Pad U1-6(31.5mm,8.825mm) or
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-6(31.5mm,8.825mm) on Top Layer And Pad U1-7(32mm,8.825mm) or
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U1-7(32mm,8.825mm) on Top Layer And Pad U1-8(32.5mm,8.825mm) or
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-1(30.325mm,18.25mm) on Top Layer And Pad
Maniman Somer Mask Sincer Constraint: (0.047mm < 0.254mm) Between Pad U2-1(30.325mm,18.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-10(33.175mm,17.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-10(33.175mm,17.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-10(33.175mm,17.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-11(33.175mm,17.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-11(33.175mm,17.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-12(33.175mm,18.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-13(32.5mm,18.925mm) on Top Layer And Pad
Manifa (and resorted as the street of the constraint: (0.022mm < 0.254mm) Between Pad U2-13(32.5mm, 18.925mm) on Top Layer And Pad
Mahin/(ahi. State) on Top Layer And Pad
Manifa(ani.5moletei &/Asstrostrojer Constraint: (0.022mm < 0.254mm) Between Pad U2-14(32mm,18.925mm) on Top Layer And Pad U2-17(31.75mm,17.5mm
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-15(31.5mm,18.925mm) on Top Layer And Pad
Manifo(ជាក់ទេសៅ៨មិ: Massix ទេព័រver Constraint: (0.022mm < 0.254mm) Between Pad U2-15(31.5mm,18.925mm) on Top Layer And Pad
Manin Sonder, Wasknish)ver Constraint: (0.022mm < 0.254mm) Between Pad U2-16(31mm, 18.925mm) on Top Layer And Pad U2-17(31.75mm, 17.5mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad
Manarata Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad
Mana (30na Souter, Mass rother,
Manif(30n3 85inder, Mass 18th)er Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad U2-5(31mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad U2-6(31.5mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad U2-7(32mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad U2-8(32.5mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.022mm < 0.254mm) Between Pad U2-17(31.75mm,17.5mm) on Top Layer And Pad
Mian (3.2m) Storology, Maa Star Strover Constraint: (0.047mm < 0.254mm) Between Pad U2-2(30.325mm, 17.75mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-3(30.325mm,17.25mm) on Top Layer And Pad
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-5(31mm,16.075mm) on Top Layer And Pad U2-6(31.5mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-6(31.5mm,16.075mm) on Top Layer And Pad U2-7(32mm,16.075mm)
Minimum Solder Mask Sliver Constraint: (0.047mm < 0.254mm) Between Pad U2-7(32mm,16.075mm) on Top Layer And Pad U2-8(32.5mm,16.075mm)
on

Tuesday 26 Mar 2019 9:36:57 PN. Page 3 of 3